# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date	
SHINTARO KOGURA	09/18/2015	
RYOTA SASAJIMA	09/18/2015	

## **RECEIVING PARTY DATA**

Name:	HITACHI KOKUSAI ELECTRIC INC.
Street Address:	14-1, SOTOKANDA 4-CHOME
Internal Address:	CHIYODA-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	101-8980

## **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	14859855

## **CORRESPONDENCE DATA**

**Fax Number:** (215)568-6499

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

**Phone:** 215-568-6400

Email: MGORDON@VKLAW.COM

Correspondent Name: DANIEL N. CALDER Address Line 1: VOLPE & KOENIG

Address Line 2: 30 SOUTH 17TH STREET

Address Line 4: PHILADELPHIA, PENNSYLVANIA 19103

ATTORNEY DOCKET NUMBER:	HITACHI13-0001140US01
NAME OF SUBMITTER:	DANIEL N. CALDER
SIGNATURE:	/Daniel N. Calder/
DATE SIGNED:	09/21/2015

### **Total Attachments: 4**

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> PATENT REEL: 036612 FRAME: 0803

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PATENT REEL: 036612 FRAME: 0804

#### ASSIGNMENT AND DECLARATION

With respect to the invention titled

# METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE, SUBSTRATE PROCESSING APPARATUS, AND RECORDING MEDIUM

for which the undersigned has authorized or prepared an application for United States Letters Patent, U.S. Patent Application No. 14/859,855 , filed on September 21, 2015 I (the undersigned) hereby state the following.

#### **DECLARATION**

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations § 1.56.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than 5 years, or both.

#### ASSIGNMENT

The undersigned hereby authorizes assignee or assignee's representative to insert the Application Number and the filing date of this application if they are unknown at the time of execution of this assignment.

Assignee	HITACHI KOKUSAI ELECTRIC INC.	
Assignee State or Country of Incorporation	Japan	
Assignee Address	14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 1018980, Japan	

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Assignee is desirous of acquiring the entire right, title and interest in the invention, all applications for and all letters patent issued on the invention.

For good and valuable consideration, the receipt and sufficiency of which is acknowledged, the undersigned, intending to be legally bound, does hereby sell, assign and transfer to the assignee and assignee's successors, assigns and legal representatives the entire right, title and interest in the invention and all patent applications thereon, including, but not limited to, the application for United States Letters Patent entitled as above, and all divisions and continuations thereof, and in all letters patent, including all reissues and reexaminations thereof, throughout the world, including the right to claim priority under the Paris Convention or other treaty.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, to supply all information and evidence relating to the making and practice of the invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention throughout the world for the benefit of the assignee, and to execute all instruments proper to carry out the intent of this instrument.

The undersigned warrants that the rights and property herein conveyed are free and clear of any encumbrance.

AND this Assignment may be executed in multiple counterparts, each of which shall be deemed to be an original of this Assignment. Additionally, the undersigned hereby authorizes our attorneys to collect the signature pages of each executed counterpart and to attach those signature pages to a single copy of this instrument, which single copy and attached signature pages together shall constitute an original of this Assignment.

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# SIGNATURE SHEET FOR DECLARATION AND ASSIGNMENT

Inventor's Name	KOGURA, Shintaro	
Inventor's Signature	Shintaro Kogura	
Date	September 18, 2015	
Signed at	Toyama-shi, Japan	
	(City and Country)	
STATEM	ENT OF WITNESS (optional):	
	Ι,	
	Name of Witness	
was perso	onally present and did see KOGURA, Shintaro inventor identified above	
execute th	nis Assignment on and such Assignor is personally know date	n
to me to b	e the person described herein.	
Witness Signature		
must accom	ion data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, apany this form. Use a separate form for each inventor; or check the box below and e attached page(s) to list additional inventors.	

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■ Additional inventors are being named on the \_1\_ supplemental sheet(s) attached hereto.

# SUPPLEMENTAL SHEET FOR DECLARATION AND ASSIGNMENT

Inventor's Name	SASAJIMA, Ryota	
Inventor's Signature	Rora Scsafina September 18, 2015	
Date	September 18 2015	
Signed at	Toyama-shi, Japan	
	(City and Country)	
STATEM	IENT OF WITNESS (optional):	
	I,	
	Name of Witness	
was perso	onally present and did see SASAJIMA, Ryota	
	inventor identified above	
execute th	his Assignment on and such Assignor is persona date	ılly known
to me to b	be the person described herein.	
Witness		

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